



Material Content Data Sheet



Sales Product Name		BSZ0502NSI		Issued		20. July 2018		
MA#		MA001300030						
Package		PG-TSDSON-8-25		Weight*		34.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.326	0.94	0.94	9431	9431
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		105	
	non noble metal	zinc	7440-66-6	0.015	0.04		421	
	non noble metal	iron	7439-89-6	0.291	0.84		8410	
wire	non noble metal	copper	7440-50-8	11.804	34.15	35.04	341489	350425
	non noble metal	copper	7440-50-8	0.017	0.05	0.05	478	478
	encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1049
	plastics	epoxy resin	-	1.867	5.40		54014	
	inorganic material	silicondioxide	60676-86-0	16.224	46.94	52.44	469346	524409
leadfinish	non noble metal	tin	7440-31-5	0.400	1.16	1.16	11578	11578
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	588	588
solder	noble metal	silver	7440-22-4	0.013	0.04		381	
	non noble metal	tin	7440-31-5	0.011	0.03		305	
	non noble metal	lead	7439-92-1	0.503	1.46	1.53	14560	15246
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		105	
	non noble metal	iron	7439-89-6	0.073	0.21		2108	
	non noble metal	copper	7440-50-8	2.959	8.56	8.78	85606	87845
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com